

# Positive Floating Hot Swap Power Manager

## FEATURES

- Precision Fault Threshold
- Programmable Average Power Limiting
- Programmable Linear Current Control
- Programmable Overcurrent Limit
- Programmable Fault Time
- Internal Charge Pump to Control External NMOS Device
- Fault Output and Catastrophic Fault Indication
- Fault Mode Programmable to Latch or Retry
- Shutdown Control
- Undervoltage Lockout

## DESCRIPTION

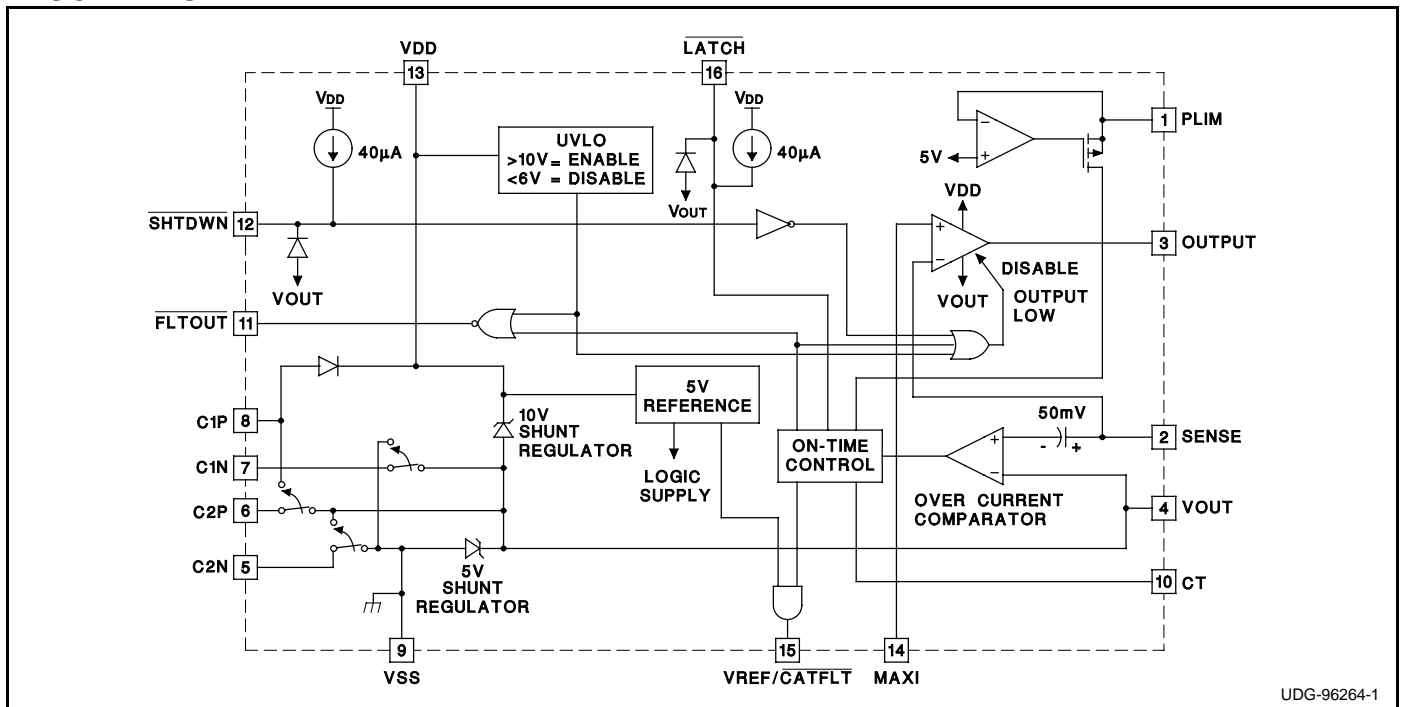
The UCC3917 family of positive floating hot swap managers provides for complete power management, hot swap, and fault handling capability for PC boards. The voltage limitation of the application is only restricted by the external component voltage limitation and not the IC. The IC provides its own supply rail via a charge pump off of VOUT. The charge pump derives its power from the onboard 5V shunt regulator, and thus, IDD is provided by the output load. The onboard 10V shunt regulator protects the IC from excess voltage. The IC also has catastrophic fault indication to alert the user that the ability to shut off the output NMOS has been bypassed. All control and housekeeping functions are integrated and externally programmable. These include the fault current level, maximum output sourcing current, maximum fault time, soft start time, and average NMOS power limiting. In the event of a constant fault, the internal timer will limit the on time/off time ratio from less than 0.1% to a maximum 3%, depending on the fault condition. In order to maintain constant average output power, the PLIM pin is provided to sense the drain voltage of the external NMOS through a resistor, and modulate duty cycle accordingly.

The fault level across the current sense amplifier is fixed at 50mV to minimize total drop out. Once 50mV is exceeded across the current sense resistor, the fault timer will start. The maximum allowable sourcing current is programmed with a voltage divider from the VREF/CATFLT pin to generate a fixed voltage on the MAXI pin. The current level at which the output appears as a current source is equal to VMAXI divided by the current sense resistor. If desired, a controlled current startup can be programmed with a capacitor on MAXI.

When the output current is below the fault level, the output device is switched on with full gate drive. When the output current exceeds the fault level, but is

Continued

## BLOCK DIAGRAM



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## DESCRIPTION (cont.)

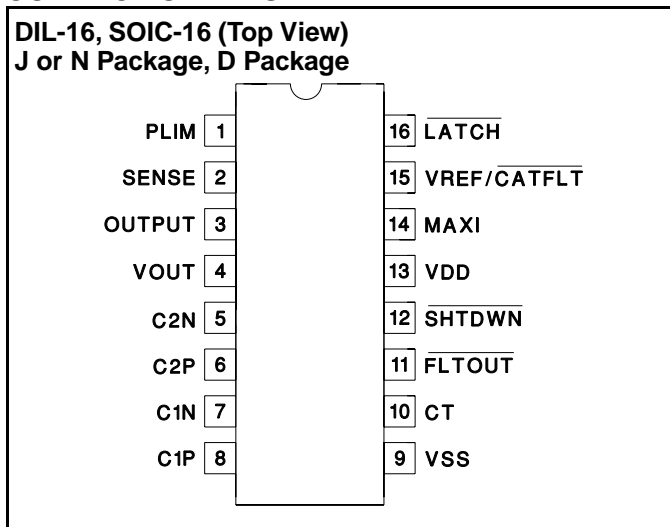
less than maximum allowable sourcing level programmed by MAXI, the output remains switched on, and the fault timer starts charging CT. Once CT charges to 2.5V, the output device is turned off and attempts either a retry sometime later or waits for the state on the LATCH pin to charge if in latch mode. When the output current reaches the maximum sourcing current level, the output device appears as a current source.

## ABSOLUTE MAXIMUM RATINGS

IDD	5mA
SHTDWN Current	250 $\mu$ A
LATCH Current	250 $\mu$ A
VREF Current	250 $\mu$ A
PLIM Current	5mA
MAXI Input Voltage	VIN
Storage Temperature	-65°C to +150°C
Junction Temperature	-55°C to +150°C
Lead Temperature (Soldering, 10 sec.)	+300°C

Currents are positive into, negative out of the specified terminal.  
Consult Packaging Section of Databook for thermal limitations and considerations of package.

## CONNECTION DIAGRAM



**ELECTRICAL CHARACTERISTICS:** Unless otherwise specified, TA = 0°C to 70°C for the UCC3917, -40°C to 85° for the UCC2917 and -55°C to 125°C for the UCC1917, CT = 4.7nF. TA = TJ.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
<b>VCC Section</b>					
Icc	From VOUT (Note 2)		5		mA
UVLO Turn On Threshold		8	9	10	V
UVLO Off Voltage		5.5	6.5	7.5	V
VSS Regulator Voltage		-6	-5	-4	V
<b>Fault Timing Section</b>					
Overcurrent Threshold	TA = 25°C	47.5	50	53	mV
	Over Operating Temperature	46	50	53.5	mV
Overcurrent Input Bias			50	500	nA
CT Charge Current	VCT = 1V	-70	-50	-36	$\mu$ A
CT Discharge Current	VCT = 1V	0.9	1.5	2.1	$\mu$ A
CT Fault Threshold		2.25	2.5	2.75	V
CT Reset Threshold		0.32	0.5	0.62	V
Output Duty Cycle	Fault Condition	1.7	2.7	3.7	%
<b>Output Section</b>					
Output High Voltage	IOUT = $\theta$	VIN+6	VIN+8	VIN+10	V
	IOUT = -500 $\mu$ A	VIN+5	VIN+7	VIN+9	V
Output Low Voltage	IOUT = $\theta$		0	0.05	V
	IOUT = 500 $\mu$ A		0.1	0.5	V
	IOUT = 1mA		0.5	0.9	V
<b>Linear Current Section</b>					
Sense Control Voltage	MAXI = 100mV	85	100	115	mV
	MAXI = 400mV	370	400	430	mV
Input Bias	MAXI = 200mV		50	500	nA

**ELECTRICAL CHARACTERISTICS:** Unless otherwise specified, T<sub>A</sub> = 0°C to 70°C for the UCC3917, -40°C to 85° for the UCC2917 and -55°C to 125°C for the UCC1917, C<sub>T</sub> = 4.7nF. T<sub>A</sub> = T<sub>J</sub>.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
<b>SHUTDOWN Section</b>					
Shutdown Threshold		2.0	2.4	2.8	V
Input Current	SHTDWN = 0V	24	40	56	μA
Shutdown Delay			100	500	ns
<b>LATCH Section</b>					
Latch Threshold		1.7	2	2.3	V
Input Current	LATCH = 0V	24	40	56	μA
<b>Fault Out Section</b>					
Fault Output High		4	5	6	V
Fault Output Low			0.01	0.05	V
<b>Power Limiting Section</b>					
V <sub>SENSE</sub> Regulator Voltage	I <sub>PLIMIT</sub> = 64μA	4	5	6	V
Duty Cycle Control	I <sub>PLIMIT</sub> = 64μA	0.6	1.2	1.7	%
	I <sub>PLIMIT</sub> = 1mA	0.045	0.1	0.2	%
<b>VREF/CATFLT Section</b>					
V <sub>REF</sub> Regulator Voltage		4	5	6	V
Fault Output Low			0.01	0.05	V
Output Sink Current	V <sub>CT</sub> = 5V	2	5	8	mA
Overload Comporator Threshold	Relative to MAXI	140	200	260	mV

Note 1: All voltages are with respect to V<sub>OUT</sub>. Current is positive into and negative out of the specified terminal.

Note 2: Set by user with R<sub>3</sub> and R<sub>ss</sub>

## PIN DESCRIPTIONS

**C1N:** Negative side of the upper charge pump capacitor.

**C1P:** Positive side of the upper charge pump capacitor.

**C2N:** Negative side of the lower charge pump capacitor.

**C2P:** Positive side of lower charge pump capacitor.

**CT:** A capacitor is connected to this pin to set the maximum fault time. The maximum fault time must be more than the time to charge the external load capacitance (see Application Information). The maximum fault time is defined as

$$T_{\text{FAULT}} = \frac{2 \cdot C_T}{I_{\text{CH}}}$$

where I<sub>CH</sub> = 36μA + I<sub>PLIM</sub>, and I<sub>PLIM</sub> is the current into the power limit pin. Once the fault time is reached, the output will shutdown for a time given by: T<sub>SD</sub> = 2 • 10<sup>6</sup> • C<sub>T</sub>.

**FLTOUT:** This pin provides fault output indication. Interface to this pin is usually performed through level shift transistors. Under a non-fault condition, FLTOUT will pull to a high state. When a fault is detected by the fault timer or the under voltage lockout, this pin will drive to a low state, indicating the output NMOS is in the off state.

**LATCH:** Pulling this pin low causes a fault to latch until this pin is brought high or a power on reset is attempted. However, pulling this pin high before the reset time is reached will not clear the fault until the reset time is reached. Keeping LATCH high will result in normal operation of the fault timer. Users should note there will be an RC delay dependent upon the external capacitor at this pin.

**MAXI:** This pin programs the maximum allowable sourcing current. Since V<sub>REF</sub>/CATFLT is a regulated voltage, a voltage divider can be derived to generate the program level for MAXI. The current level at which the output appears as a current source is equal to the voltage on MAXI over the current sense resistor. If desired, a controlled current start up can be programmed with a capacitor on MAXI (to V<sub>OUT</sub>), and a programmed start delay can be achieved by driving the shutdown with an open collector/drain device into an RC network.

**OUTPUT:** Output device to the NMOS pass element.

**PLIM:** This feature ensures that the average NMOS power dissipation is controlled. A resistor is connected from this pin to the drain of the NMOS pass element.

**PIN DESCRIPTIONS (cont.)**

When the voltage across the NMOS exceeds 5V, current will flow into PLIM which adds to the fault timer charge current, reducing the duty cycle from the 3% level.

**SENSE:** Input voltage from the current sense resistor. When there is greater than 50mV across this pin with respect to VOUT, a fault is sensed, and CT starts to charge.

**SHTDWN:** This pin provides shutdown control. Interface to this pin is usually performed through level shift transistors. When shutdown is driven low, the output disables the NMOS pass device. When brought high, shutdown is disabled and the IC functions as intended. Users should note there will be an RC delay to the output dependent upon the external capacitor at this pin.

**VDD:** Power to the chip. On startup, power is current fed from a resistor (and a series diode) to VIN. In normal op-

eration, power will be supplied by the charge pump.

**VOUT:** Ground reference for the IC.

**VREF/CATFLT:** This pin primarily provides an output reference for the programming of MAXI. Secondly, it provides catastrophic fault output indication. Under a catastrophic fault, when the IC is unsuccessfully attempting to shutdown the NMOS pass device, this pin will pull to a low state. In an application, this pin could be connected to a second NMOS transistor in series with the main NMOS for redundancy. Due to the primary function of this pin, full gate drive would not be available to the second NMOS.

**VSS:** Negative reference out of the chip. Normally current fed via a resistor to ground.

**APPLICATION INFORMATION**

**Fault Timing**

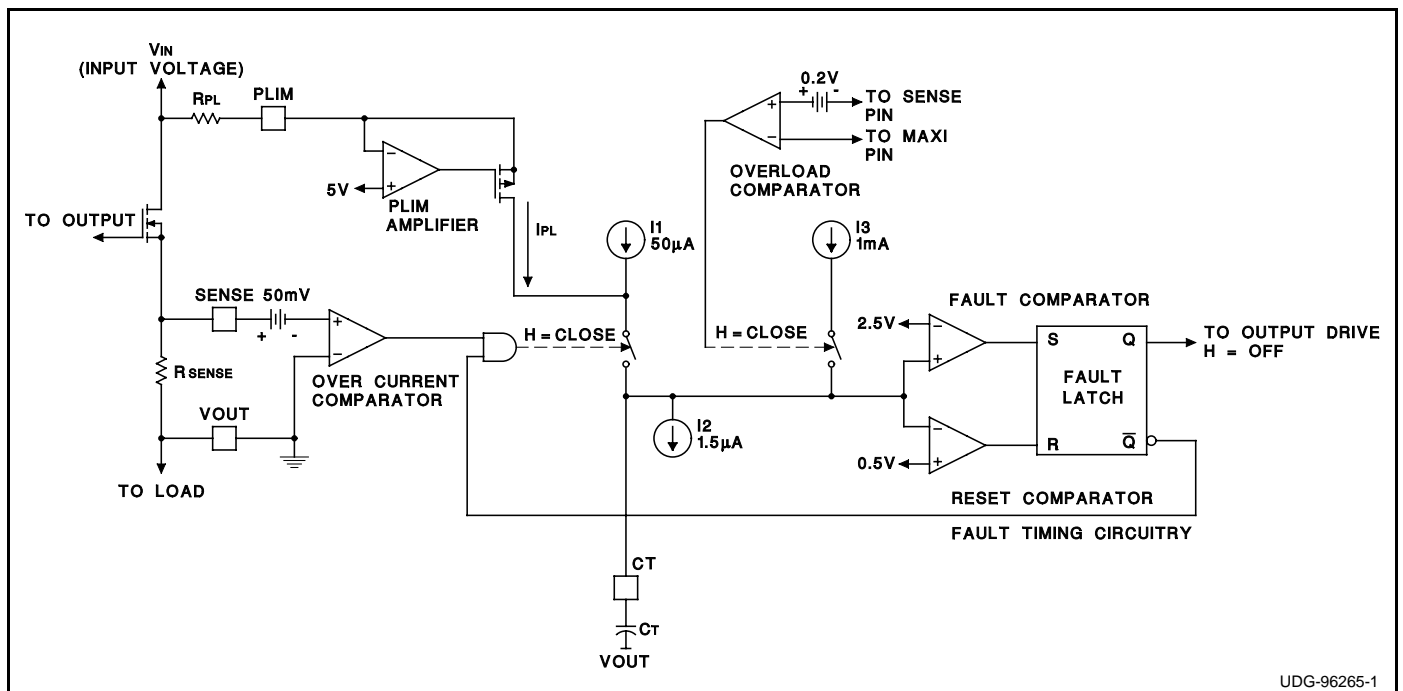
Figure 1 shows the detailed circuitry for the fault timing function of the UCC3917. For simplicity, we first consider a typical fault mode where the overload comparator and the current source I3 do not come into play. A typical fault occurs once the voltage across the current sense resistor, RS, exceeds 50mV. This causes the over current comparator to trip and the timing capacitor to charge with current source I1 plus the current from the power limiting amplifier, or PLIM amplifier. The PLIM amplifier is designed to only source current into the CT pin and to begin sourcing current once the voltage across the output FET

exceeds 5V. The current IPL is related to the voltage across the FET with the following expression:

$$I_{PL} = \frac{(V_{IN} - V_{OUT}) - 5V}{R_{PL}}$$

Later, it will be shown how this feature will limit average power dissipation in the pass device. Note that under normal fault conditions where the output current is just above the fault level,  $V_{OUT} \cong V_{IN}$ ,  $I_{PL} = 0$ , and the CT charging current is just I1 or 50µA.

During a fault, CT will charge at a rate determined by the internal charging current and the external timing capaci-



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**Figure 1. Fault Timing Circuitry for the UCC3917, Including Power Limit and Overload.**

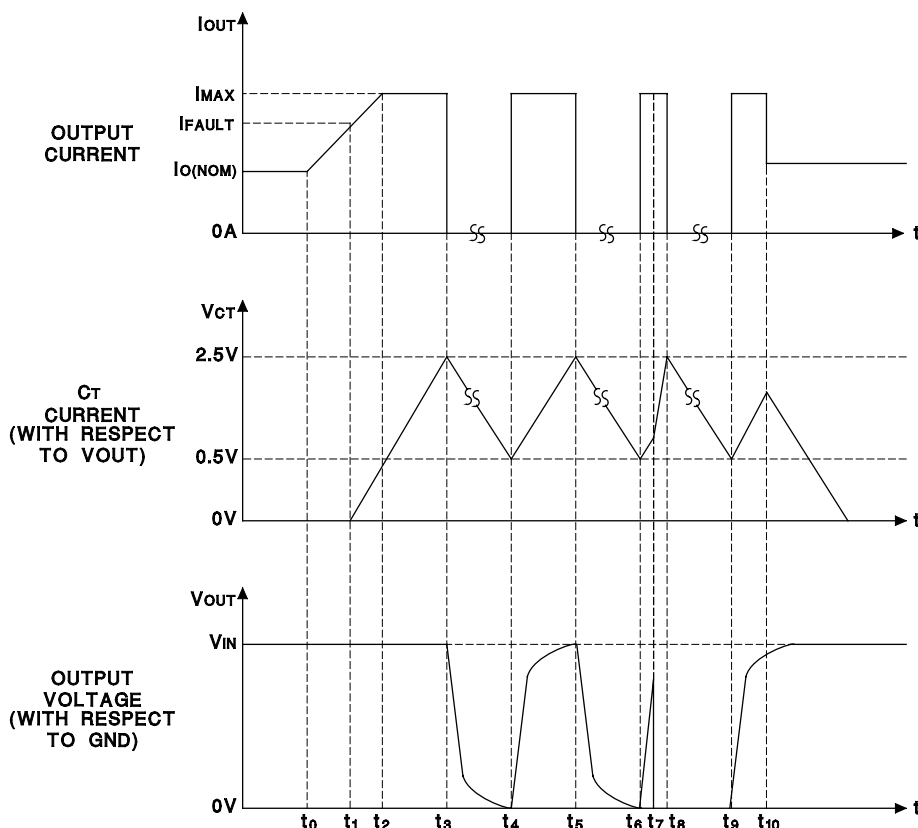
**APPLICATION INFORMATION (cont.)**

tor. Once CT charges to 2.5V, the fault comparator switches and sets the fault latch. Setting the fault latch causes both the output to switch off and the charging switch to open. CT must now discharge with current source I2 until 0.5V is reached. Once the voltage at CT reaches 0.5V, the fault latch resets (assuming LATCH is high, otherwise the fault latch will not reset until the LATCH pin is brought high or a power-on reset occurs) which re-enables the output and allows the fault circuitry

to regain control of the charging switch. If a fault is still present, the overcurrent comparator will close the charging switch causing the cycle to repeat. Under a constant fault the duty cycle is given by:

$$\text{Duty Cycle} = \frac{1.5\mu\text{A}}{I_{PL} + 50\mu\text{A}}$$

where I<sub>PL</sub> is 0μA under normal operations (see Figure 2).



UDG-96266

**t<sub>0</sub>**: Safe condition - output current is nominal, output voltage is at the positive rail, V<sub>IN</sub>.

**t<sub>1</sub>**: Fault control reached - output current rises above the programmed fault value, CT begins to charge with  $\cong 36\mu\text{A}$ .

**t<sub>2</sub>**: Maximum current reached - output current reaches the programmed maximum level and becomes a constant current with value I<sub>MAX</sub>.

**t<sub>3</sub>**: Fault occurs - CT has charged to 2.5V, fault output goes high, the FET turns off allowing no output current to flow, V<sub>OUT</sub> discharges to ground.

**t<sub>4</sub>**: Retry - CT has discharged to 0.5V, but fault current is still exceeded, CT begins charging again, FET is on, V<sub>OUT</sub> rises to V<sub>IN</sub>.

**t<sub>5</sub> = t<sub>3</sub>**: Illustrates 3% duty cycle.

**t<sub>6</sub> = t<sub>4</sub>**:

**t<sub>7</sub>**: Output short circuit - if V<sub>OUT</sub> is short circuited to ground, CT charges at a higher rate depending upon the values for V<sub>IN</sub> and R<sub>PL</sub>.

**t<sub>8</sub>**: Fault occurs - output is still short circuited, but the occurrence of a fault turns the FET off so no current is conducted.

**t<sub>9</sub> = t<sub>4</sub>**: Output short circuit released, still in fault mode.

**t<sub>10</sub> = t<sub>0</sub>**: Fault released, safe condition - return to normal operation of the circuit breaker.

Note that  $t_6 - t_5 \cong 36 \cdot (t_5 - t_4)$ .

**Figure 2. Nominal Timing Diagram**

### APPLICATION INFORMATION (cont.)

However, under large transients, average power dissipation can be limiting using the PLIM pin. A proof follows, average dissipation in the pass element is given by:

$$P_{FET\ AVG} = (V_{IN} - V_{OUT}) \cdot I_{MAX} \cdot \text{Duty Cycle}$$

$$= (V_{IN} - V_{OUT}) \cdot I_{MAX} \cdot \frac{1.5\mu A}{I_{PL} + 50\mu A}$$

Where  $(V_{IN} - V_{OUT}) \gg 5V$ ,

$$I_{PL} \cong \frac{V_{IN} - V_{OUT}}{R_{PL}}$$

and where  $I_{PL} \gg 50\mu A$ , the duty cycle can be approximated as:

$$\frac{1.5\mu A \cdot R_{PL}}{V_{IN} - V_{OUT}}$$

Therefore the average power dissipation in the MOSFET can be approximated by:

$$P_{FET\ AVG} = (V_{IN} - V_{OUT}) \cdot I_{MAX} \cdot \frac{1.5\mu A \cdot R_{PL}}{V_{IN} - V_{OUT}}$$

$$= I_{MAX} \cdot 1.5\mu A \cdot R_{PL}$$

Notice that since  $(V_{IN} - V_{OUT})$  cancels, average power dissipation is limited in the NMOS pass element (see Figure 3). Also, a value for  $R_{PL}$  can be roughly determined from this approximation.

$$R_{PL} = \frac{P_{FET\ AVG}}{I_{MAX} \cdot 1.5\mu A} \quad \text{with}$$

$$R_{PL(\min)} = \frac{V_{IN} - 5V}{5\mu A}$$

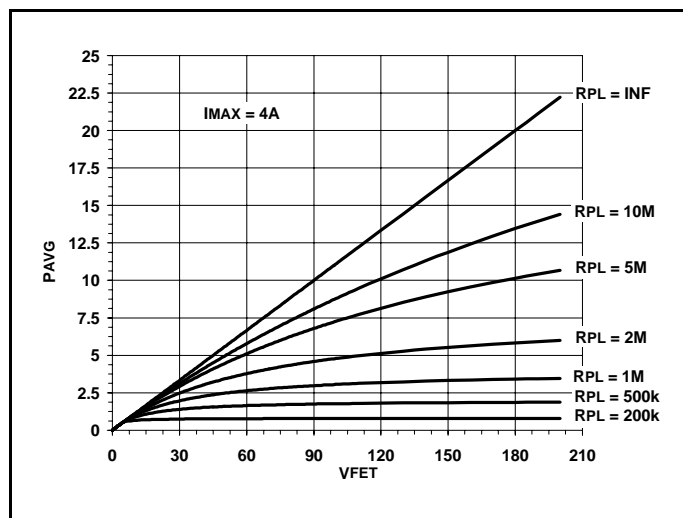


Figure 3. Plot of Average Power vs. FET Voltage for Increasing Values of RPL

### Overload Comparator

The linear amplifier in the UCC3917 ensures that the output NMOS does not pass more than  $I_{MAX}$  (which is  $V_{MAX}/R_S$ ). In the event the output current exceeds the programmed  $I_{MAX}$  by  $0.2V/R_S$ , which can only occur if the output FET is not responding to a command from the IC, CT will begin charging with  $I_3$ , 1mA, and continue to charge eventually tripping a catastrophic fault comparator not shown. This comparator will then drive  $V_{REF}/CATFLT$  low, which can be used to build redundancy into the system if desirable (as outlined in the pin description for  $V_{REF}/CATFLT$ ).

### Selecting Minimum Timing Capacitance

The startup time of the IC may not exceed the fault time for the application. Since the timing capacitor,  $C_T$ , determines the fault time, it's minimum value can be determined by first finding out the startup time. The startup time is dependent on several external components. For example, a capacitive load is required for the IC to startup, and will be referred to as  $C_{LOAD}$ .  $C_{IN}$ , also required and equal to  $0.1\mu F$ , represents the capacitor between the  $V_{DD}$  and  $V_{OUT}$  pins.

Let  $I_{MAX}$  be the maximum current allowable through the external NMOS device (programmed via  $MAXI$ , of course). Then, we can define the startup time of the IC as such:

Current Source Load:

$$T_{START} = \frac{1.2 \cdot C_{LOAD} \cdot V_{IN}}{I_{MAX} - I_{LOAD}}$$

Resistive Load:

$$T_{START} = 2 \cdot R_{LOAD} \cdot C_{LOAD} \cdot \ln \left( \frac{I_{MAX} \cdot R_{LOAD}}{I_{MAX} \cdot R_{LOAD} - V_{IN}} \right)$$

The only remaining external component which may affect the minimum timing capacitor value is the optional power limiting resistor,  $R_{PL}$ . If  $R_{PL}$  is desired, it's value can be determined from the "Fault Timing" section above. Finally, the minimum timing capacitor can now be calculated.

Current Source Load:

$$C_{Tmin} = \frac{3 \cdot T_{START} \cdot (62\mu A \cdot R_{PL} + V_{IN} - 10V)}{10V \cdot R_{PL}}$$

Resistive Load:

$$C_{Tmin} = \frac{3 \cdot T_{START} \cdot (31\mu A \cdot R_{PL} + V_{IN} - 5V - I_{MAX} \cdot R_{LOAD})}{5V \cdot R_{PL}}$$

**APPLICATION INFORMATION (cont.)**

$$+ \frac{3 \cdot R_{LOAD} \cdot V_{IN} \cdot C_{LOAD}}{5V \cdot R_{PL}}$$

If R<sub>PL</sub> is not used and PLIM is left unconnected, the equations simplify to:

$$C_{Tmin} = 18.6 \times 10^{-6} \cdot T_{START}$$

for either load condition.

**Selecting Other External Components**

Other external components are necessary for correct operation of the IC. Referring to the application diagram at the back of the data sheet, resistors R<sub>SENSE</sub>, R<sub>SS</sub>, R<sub>1</sub>, R<sub>2</sub> and R<sub>3</sub> are required and follow certain equations with a brief description following where applicable:

$$R_{SENSE} = \frac{50mV}{I_{FAULT}} \text{ (Sense Resistor)}$$

$$R_{SS} = \frac{V_{IN} - 5V}{5mA} \text{ (Connected between VSS and GND)}$$

$$R_3 = \frac{V_{IN} - 10}{5mA} \text{ (Used in series with a diode to connect}$$

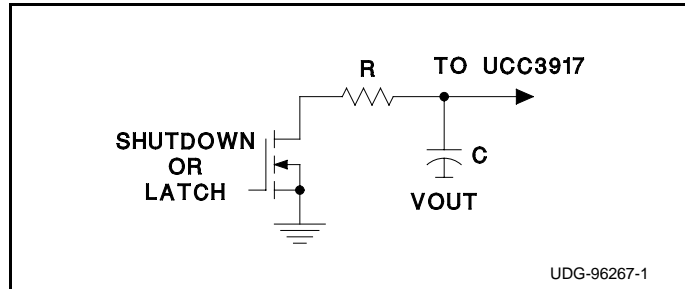
V<sub>IN</sub> to VDD)

(R<sub>1</sub> + R<sub>2</sub>) > 20kΩ (Current limit out of VREF)

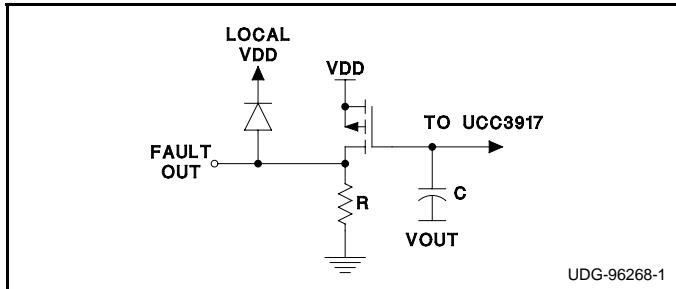
Lastly, the external capacitors used for the charge pump are required and need to equal 0.1μF, i.e. C<sub>IN</sub> = C<sub>H</sub> = C<sub>1</sub> = C<sub>2</sub> = 0.1μF.

**Level Shift Circuitry (Optional)**

The level shift circuitry shown in Figure 4 and Figure 5 represents one way of performing interface to LATCH, SHTDWN, and FLTOUT. These pins provide functionality that is not necessary for normal operation of the IC but may prove useful to the application. The resistor, R, shown in both figures is used for current limiting and follows R<sub>MIN</sub> = V<sub>IN</sub>/250μA. The capacitor, C, shown in both figures is optional to the level shift circuitry and keeps spurious signals from occurring during transients. It's minimum value is C<sub>MIN</sub> = 0.1nF. It should be noted that the use of the capacitor, C, will cause delays into and out of these pins.



**Figure 4. Potential Level Shift Circuitry to Interface to LATCH AND SHTDWN on the UCC3917**



**Figure 5. Potential Level Shift Circuitry to Interface to FLTOUT on the UCC3917**

**SAFETY RECOMMENDATIONS**

Although the UCC3917 is designed to provide system protection for all fault conditions, all integrated circuits can ultimately fail short. For this reason, if the UCC3917 is intended for use in safety critical applications where UL or some other safety rating is required, a redundant

safety device such as a fuse should be placed in series with the power device. The UCC3917 will prevent the fuse from blowing for virtually all fault conditions, increasing system reliability and reducing maintenance cost, in addition to providing the hot swap benefits of the device.

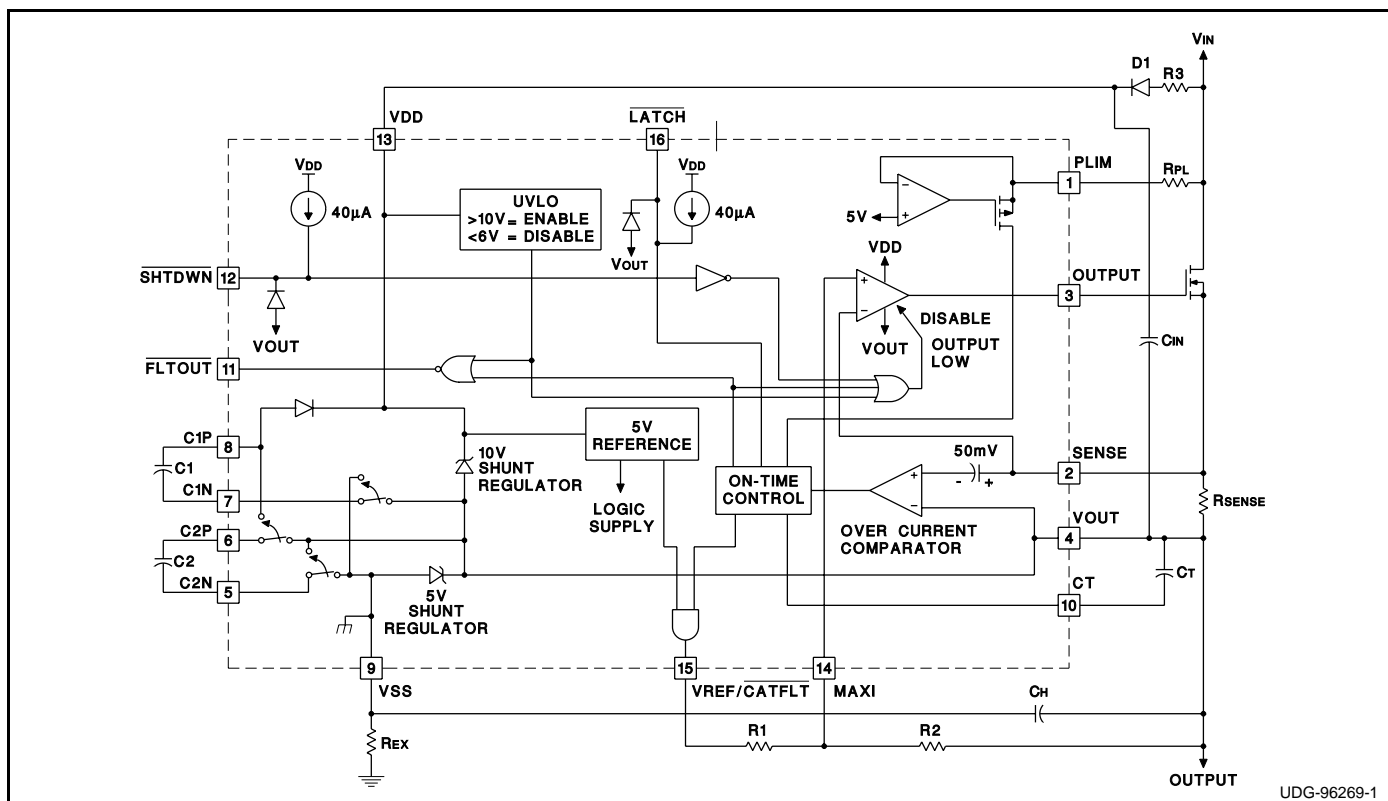


Figure 5. Positive Floating Hot Swap Power Manager